# 502147857 12/03/2012

# PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

#### **CONVEYING PARTY DATA**

Name	Execution Date
Chin-Min Lin	06/21/2007
Dun-Nian Yaung	06/21/2007
Ching-Chun Wang	06/21/2007
Tzu-Hsuan Hsu	06/21/2007
chun-Ming Su	06/21/2007

#### RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Itd.	
Street Address:	No. 8, Li-Hsin Rd. 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13692104

# **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: 24061.2370/2007-0196-C

PATENT REEL: 029391 FRAME: 0889

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	NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 3 source=2370Assignment#page1.tif source=2370Assignment#page2.tif source=2370Assignment#page3.tif		

PATENT REEL: 029391 FRAME: 0890

Docker No.: 2007-0196 / 24061.926 Customer No.: 42717

#### ASSIGNMENT

WHEREAS, we,

(1)	Chin-Min Lin	of	19F-2, No. 25, Jianjhong 1st Road Hsinchu City 300, Taiwan, R.O.C.
(2)	Dun-Nian Yaung	of	4F, No. 15, Lane 130, Wansheng Street, Wunshan District Taipei City 116, Taiwan, R.O.C.
(3)	Ching-Chun Wang	of	3F-1, No. 28, Lane 158, Sec. 2, Dongmen Road Tainan, Taiwan, R.O.C.
(4)	Tzu-Hsuan Hsu	of	No. 72, Gangshan Central Street, Cianjhen District Kaohsiung City 806, Taiwan, R.O.C.
(5)	Chun-Ming Su	of	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, R.O.C.

have invented certain improvements in

# APPARATUS AND METHOD FOR REDUCING OPTICAL CROSS-TALK IN IMAGE SENSORS

for which we have	executed an application for Letters Patent of the United States of America,
X	of even date filed herewith; and filed on July 17, 2007 and assigned application number 11/779,122; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

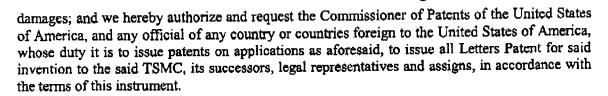
NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past

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Customer No.: 42717



AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Chin-Min Lin

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Hsinchu City 300, Taiwan, R.O.C.

Dated: 6/7/ -700

CHIN-MIN LIN.

Inventor Signature

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DOCKET INO.: 2007-01907 24001.920

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Dated: 6/21 67

Tru - Hsucy + 154.
Inventor Signature

Inventor Name:

Chun-Ming Su

Residence Address:

Dated: 6/21, >007

Chun-Ming Su Inventor Signature

R-926 - Assignment

**RECORDED: 12/03/2012** 

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**PATENT** REEL: 029391 FRAME: 0893